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Wafer dicing is a method that is much in vogue in the semiconductor industry. This method is used to separate a die from a wafer of semiconductor. This task is accomplished through several means like breaking and scribing, mechanical sawing, or through laser cutting. A wafer dicing machine is used to cut wafers into individual or separate semiconductor chips, with the aid of dicing blades.

The various methods of wafer dicing include:

â€¢ Breaking and scribing â€“ this is primarily done in a substrate, which is made of brittle material. This helps in achieving a good quality cutting surface of the substrate, without any major defects like chippings o the substrate. In this process of semiconductor wafer separation, a stress is created in the water and then along the stress line, the wafer is fractured..

â€¢ Mechanical sawing â€“ this is done with the aid of a mechanical machine called the dicing saw. This process is used primarily for a micro electro-mechanical system semiconductor device. Although, this method is still in use, it is gradually becoming unpopular due to several disadvantages; it is a slow process, it releases contaminants, and several others.

â€¢ Laser cutting â€“ this is a more technology which is used for cutting semiconductor materials. In this process, the unwanted parts are burned away, leaving behind an edge which has a high-quality finished surface.

In the entire process of wafer dicing, the dicing blades play a very important part. Various types are dicing blades are employed for this purpose. Some among them are:

â€¢ Hubbed Nickel Bonded Blades.

â€¢ Hubbed Resin Bonded Blades.

â€¢ Metal Sintered Dicing Blades.

â€¢ Hubless Resin Bonded Blades.

Thus, for those who want to embark upon the process of dicing wafers, the above information shall prove to be useful for them.

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